



Investigation of Radiated Emissions from the Printed Circuit Boards and Cables of Electronic Devices

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Message from the Guest Editor

Dear Colleagues,

Electromagnetic (EM) emissions from integrated circuits, transmission lines, and cables of electronic devices (EDs) may interfere with other EDs and with elements of the same system, which can cause noncompliance of electromagnetic compatibility (EMC) and disturbance of signal integrity in electronic product design. The future challenges in the EMC of EDs are driven by the increasing bandwidth and decreasing transient times of EM fields and signals, as well as the continued miniaturization of the components.

Topics of primary interest include but are not limited to:

- Near-field measurements of spurious emissions from the printed circuit boards and cables of electronic devices;
- Statistical processing of the registered data in time-frequency domains using cyclostationary properties;
- Localization and identification of noise sources on the surface of the PCB and inside the enclosure of the electronic device;
- Prediction of the emitted electromagnetic interference propagation in the environment of the ED;
- The influence of emissions on inter-system and intra-system EMC, in particular on the bit error rate (BER) of the communication links.





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Message from the Editor-in-Chief

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